Renesas Electronics America Inc - R7FS5D57A3A01CFB#AA0 Datasheet

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, MMC/SD, QSPI, SCI, SPI, SSI, UART/USART, USB
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	110
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	32K x 8
RAM Size	384K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 22x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LFQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r7fs5d57a3a01cfb-aa0

Table 1.8 Communication interfaces (2 of 2)

Feature	Functional description
Ethernet MAC (ETHERC)	One-channel Ethernet MAC Controller (ETHERC) compliant with the Ethernet/IEEE802.3 Media Access Control (MAC) layer protocol. An ETHERC channel provides one channel of the MAC layer interface, connecting the MCU to the physical layer LSI (PHY-LSI) that allows transmission and reception of frames compliant with the Ethernet and IEEE802.3 standards. The ETHERC is connected to the Ethernet DMA Controller (EDMAC) so data can be transferred without using the CPU. See section 29, Ethernet MAC Controller (ETHERC) in User's Manual.
SD/MMC Host Interface (SDHI)	The SDHI and MultiMediaCard (MMC) interface module provides the functionality required to connect a variety of external memory cards to the MCU. The SDHI supports both 1- and 4-bit buses for connecting memory cards that support SD, SDHC, and SDXC formats. When developing host devices that are compliant with the SD Specifications, you must comply with the SD Host/Ancillary Product License Agreement (SD HALA). The MMC interface supports 1-bit, 4-bit, and 8-bit MMC buses that provide eMMC 4.51 (JEDEC Standard JESD 84-B451) device access. This interface also provides backward compatibility and supports high-speed SDR transfer modes. See section 41, SD/MMC Host Interface (SDHI) in User's Manual.

Table 1.9 Analog

Feature	Functional description
12-Bit A/D Converter (ADC12)	Up to two successive approximation 12-Bit A/D Converters are provided. In unit 0, up to 13 analog input channels are selectable. In unit 1, up to 9 analog input channels, the temperature sensor output, and an internal reference voltage are selectable for conversion. The A/D conversion accuracy is selectable from 12-bit, 10-bit, and 8-bit conversion, making it possible to optimize the tradeoff between speed and resolution in generating a digital value. See section 45, 12-Bit A/D Converter (ADC12) in User's Manual.
12-Bit D/A Converter (DAC12)	The DAC12 D/A converts data and includes an output amplifier. See section 46, 12-Bit D/A Converter (DAC12) in User's Manual.
Temperature Sensor (TSN)	The on-chip temperature sensor can determine and monitor the die temperature for reliable operation of the device. The sensor outputs a voltage directly proportional to the die temperature, and the relationship between the die temperature and the output voltage is linear. The output voltage is provided to the ADC12 for conversion and can also be used by the end application. See section 47, Temperature Sensor (TSN) in User's Manual.
High-Speed Analog Comparator (ACMPHS)	Analog comparators can be used to compare a test voltage with a reference voltage and to provide a digital output based on the conversion result. Both the test and reference voltages can be provided to the comparator from internal sources such as the DAC12 output and internal reference voltage, and an external source. Such flexibility is useful in applications that require go/no-go comparisons to be performed between analog signals without necessarily requiring A/D conversion. See section 48, High-Speed Analog Comparator (ACMPHS) in User's Manual.

Table 1.10 Human machine interfaces

Feature	Functional description
Capacitive Touch Sensing Unit (CTSU)	The Capacitive Touch Sensing Unit (CTSU) measures the electrostatic capacitance of the touch sensor. Changes in the electrostatic capacitance are determined by software, which enables the CTSU to detect whether a finger is in contact with the touch sensor. The electrode surface of the touch sensor is usually enclosed with an electrical insulator so that fingers do not come into direct contact with the electrodes. See section 49, Capacitive Touch Sensing Unit (CTSU) in User's Manual.

Table 1.11 Graphics

Feature	Functional description
Parallel Data Capture (PDC) unit	One Parallel Data Capture (PDC) unit is provided to communicate with external I/O devices, including image sensors, and to transfer parallel data such as an image output from the external I/O device through the DTC or DMAC to the on-chip SRAM and external address spaces (the CS and SDRAM areas). See section 42, Parallel Data Capture Unit (PDC) in User's Manual.

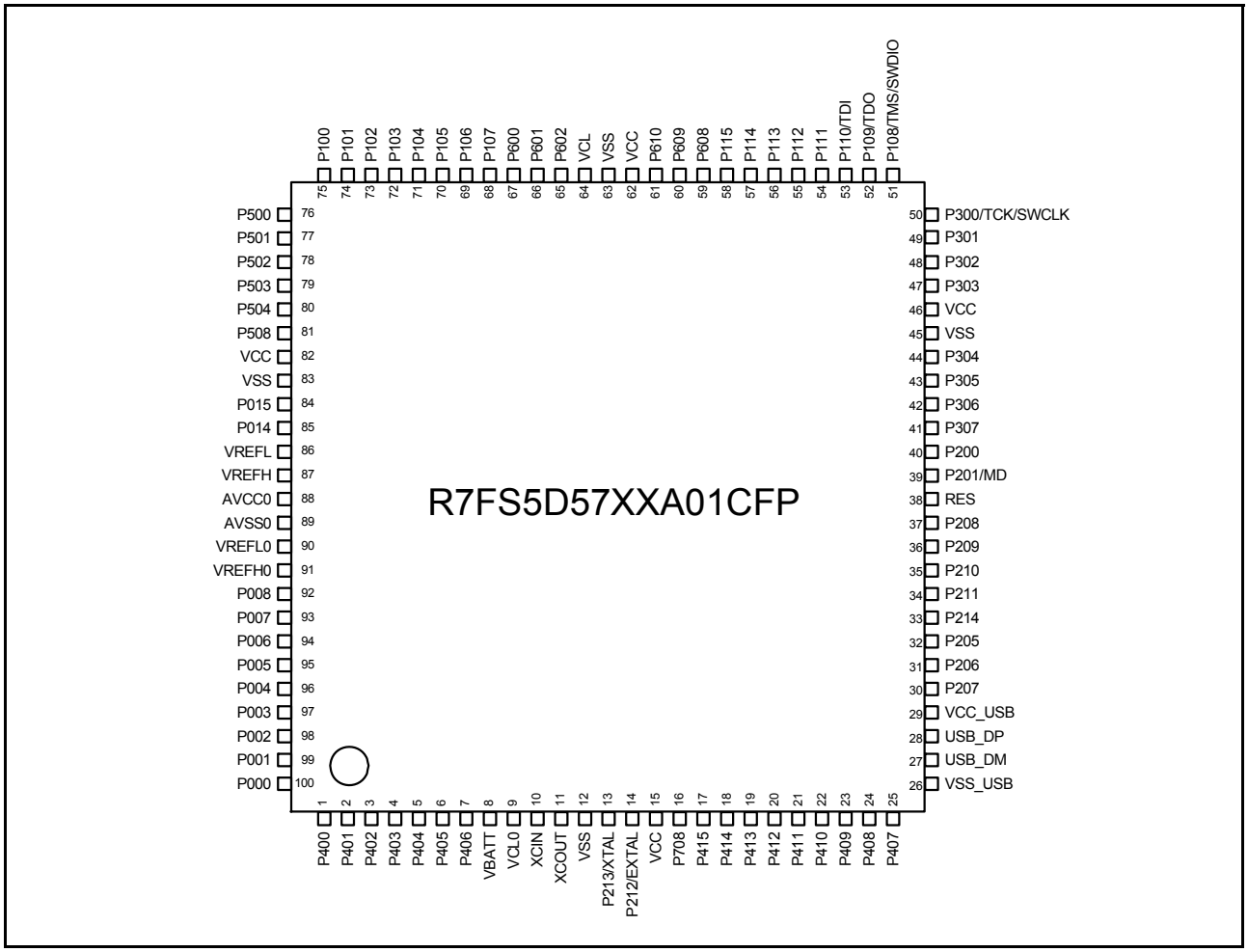


Figure 1.5 Pin assignment for 100-pin LQFP (top view)

1.7 Pin Lists

Pin number						Extbus		Timers				Communication interfaces									Analog		HMI	
LGA145	LQFP144	LQFP100	Power, System, Clock, Debug, CAC	Interrupt	I/O port	External bus	SDRAM	AGT	GPT	GPT	RTC	USBFS, CAN	SCI0,2,4,6,8 (30 MHz)	SCI1,3,5,7,9 (30 MHz)	IIC	SPI, QSPI	SSIE	ETHERC (MII) (25 MHz)	ETHERC (RMII) (50 MHz)	SDHI	ADC12	DAC12, ACMPHS	CTSU	PDC
N13	1	1	-	IRQ0	P400	-	-	AGTIO1	-	GTIOC 6A	-	-	SCK4	SCK7	SCL0 _A	-	AUDIO _CLK	ET0_WOL	ET0_WOL	-	ADTRG 1	-	-	-
L11	2	2	-	IRQ5-DS	P401	-	-	-	GTETRGA	GTIOC 6B	-	CTX0	CTS4_R TS4/SS4	TXD7/MOSI7/SDA7	SDA0 _A	-	-	ET0_MDC	ET0_MDC	-	-	-	-	-
M13	3	3	CACREF	IRQ4-DS	P402	-	-	AGTIO0/ AGTIO1	-	-	RTCIC0	CRX0	-	RXD7/MISO7/SCL7	-	-	AUDIO _CLK	ET0_MDIO	ET0_MDIO	-	-	-	-	VSYNC
K11	4	4	-	-	P403	-	-	AGTIO0/ AGTIO1	-	GTIOC 3A	RTCIC1	-	-	CTS7_R TS7/SS7	-	-	SSIBCK0_A	ET0_LINKSTA	ET0_LINKSTA	SD1DAT7_B	-	-	-	PIXD7
L12	5	5	-	-	P404	-	-	-	-	GTIOC 3B	RTCIC2	-	-	-	-	-	SSILRCK0/SSIFS0_A	ET0_EXOUT	ET0_EXOUT	SD1DAT6_B	-	-	-	PIXD6
L13	6	6	-	-	P405	-	-	-	-	GTIOC 1A	-	-	-	-	-	-	SSITXD0_A	ET0_TX_EN	RMII0_TXD_EN_B	SD1DAT5_B	-	-	-	PIXD5
J10	7	7	-	-	P406	-	-	-	-	GTIOC 1B	-	-	-	-	-	SSLB3 _C	SSIRXD0_A	ET0_RX_ER	RMII0_TXD1_B	SD1DAT4_B	-	-	-	PIXD4
H10	8	-	-	-	P700	-	-	-	-	GTIOC 5A	-	-	-	-	-	MISOB _C	-	ET0_ETXD1	RMII0_TXD0_B	SD1DAT3_B	-	-	-	PIXD3
K12	9	-	-	-	P701	-	-	-	-	GTIOC 5B	-	-	-	-	-	MOSIB _C	-	ET0_ETXD0	REF50CK0_B	SD1DAT2_B	-	-	-	PIXD2
K13	10	-	-	-	P702	-	-	-	-	GTIOC 6A	-	-	-	-	-	RSPCKB_C	-	ET0_ERXD1	RMII0_RXD0_B	SD1DAT1_B	-	-	-	PIXD1
J11	11	-	-	-	P703	-	-	-	-	GTIOC 6B	-	-	-	-	-	SSLB0 _C	-	ET0_ERXD0	RMII0_RXD1_B	SD1DAT0_B	-	VCOUT	-	PIXD0
H11	12	-	-	-	P704	-	-	AGTO0	-	-	-	CTX0	-	-	-	SSLB1 _C	-	ET0_RX_CLK	RMII0_RX_ER_B	SD1CLK_B	-	-	-	HSYNC
G11	13	-	-	-	P705	-	-	AGTIO0	-	-	-	CRX0	-	-	-	SSLB2 _C	-	ET0_CRS	RMII0_CRS_DV_B	SD1CMD_B	-	-	-	PIXCLK
J12	14	8	VBATT	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
J13	15	9	VCL0	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
H13	16	10	XCIN	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
H12	17	11	XCOUT	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
F12	18	12	VSS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
G12	19	13	XTAL	IRQ2	P213	-	-	-	GTETRGC	GTIOC 0A	-	-	-	TXD1/MOSI1/SDA1	-	-	-	-	-	-	ADTRG 1	-	-	-
G13	20	14	EXTAL	IRQ3	P212	-	-	AGTEE1	GTETRGD	GTIOC 0B	-	-	-	RXD1/MISO1/SCL1	-	-	-	-	-	-	-	-	-	-
F13	21	15	VCC	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
G10	22	-	-	-	P713	-	-	AGTOA0	-	GTIOC 2A	-	-	-	-	-	-	-	-	-	-	-	-	TS17	-
F11	23	-	-	-	P712	-	-	AGTOB0	-	GTIOC 2B	-	-	-	-	-	-	-	-	-	-	-	-	TS16	-
E13	24	-	-	-	P711	-	-	AGTEE0	-	-	-	-	-	CTS1_RTS1/SS1	-	-	-	ET0_TX_CLK	-	-	-	-	TS15	-
E12	25	-	-	-	P710	-	-	-	-	-	-	-	-	SCK1	-	-	-	ET0_TX_ER	-	-	-	-	TS14	-
F10	26	-	-	IRQ10	P709	-	-	-	-	-	-	-	-	TXD1/MOSI1/SDA1	-	-	-	ET0_ETXD2	-	-	-	-	TS13	-
D13	27	16	CACREF	IRQ11	P708	-	-	-	-	-	-	-	-	RXD1/MISO1/SCL1	-	SSLA3 _B	AUDIO _CLK	ET0_ETXD3	-	-	-	-	TS12	PCKO
E11	28	17	-	IRQ8	P415	-	-	-	-	GTIOC 0A	-	USB_VBUSEN	-	-	-	SSLA2 _B	-	ET0_TX_EN	RMII0_TXD_EN_A	SD0CD	-	-	TS11	PIXD5
D12	29	18	-	IRQ9	P414	-	-	-	-	GTIOC 0B	-	-	-	-	-	SSLA1 _B	-	ET0_RX_ER	RMII0_TXD1_A	SD0WP	-	-	TS10	PIXD4
E10	30	19	-	-	P413	-	-	-	GTOUUP	-	-	-	CTS0_RTS0/SS0	-	-	SSLA0 _B	-	ET0_ETXD1	RMII0_TXD0_A	SD0CLK_A	-	-	TS09	PIXD3
C13	31	20	-	-	P412	-	-	AGTEE1	GTOULO	-	-	-	SCK0	-	-	RSPCKA_B	-	ET0_ETXD0	REF50CK0_A	SD0CMD_A	-	-	TS08	PIX02
D11	32	21	-	IRQ4	P411	-	-	AGTOA1	GTOVUP	GTIOC 9A	-	-	TXD0/MOSI0/SDA0	CTS3_RTS3/SS3	-	MOSIA _B	-	ET0_ERXD1	RMII0_RXD0_A	SD0DAT0_A	-	-	TS07	PIX01
C12	33	22	-	IRQ5	P410	-	-	AGTOB1	GTOVLO	GTIOC 9B	-	-	RXD0/MISO0/SCL0	SCK3	-	MISOA _B	-	ET0_ERXD0	RMII0_RXD1_A	SD0DAT1_A	-	-	TS06	PIXD0
B13	34	23	-	IRQ6	P409	-	-	-	GTOWUP	GTIOC 10A	-	USB_EXICEN	-	TXD3/MOSI3/SDA3	-	-	-	ET0_RX_CLK	RMII0_RX_ER_A	-	-	-	TS05	HSYNC
D10	35	24	-	IRQ7	P408	-	-	-	GTOWLO	GTIOC 10B	-	USB_ID	-	RXD3/MISO3/SCL3	SCL0 _B	-	-	ET0_CRS	RMII0_CRS_DV_A	-	-	-	TS04	PIXCLK
A13	36	25	-	-	P407	-	-	AGTIO0	-	-	RTCOUT	USB_VBUS	CTS4_RTS4/SS4	-	SDA0 _B	SSLB3 _A	-	ET0_EXOUT	ET0_EXOUT	-	ADTRG 0	-	TS03	-
B11	37	26	VSS_USB	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
A12	38	27	-	-	-	-	-	-	-	-	-	USB_DM	-	-	-	-	-	-	-	-	-	-	-	-
B12	39	28	-	-	-	-	-	-	-	-	-	USB_DP	-	-	-	-	-	-	-	-	-	-	-	-
A11	40	29	VCC_USB	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-

Pin number						Extbus		Timers				Communication interfaces										Analog		HMI	
LGA145	LQFP144	LQFP100	Power, System, Clock, Debug, CAC	Interrupt	I/O port	External bus	SDRAM	AGT	GPT	GPT	RTC	USBFS, CAN	SCI0,2,4,6,8 (30 MHz)	SCI1,3,5,7,9 (30 MHz)	IIC	SPI, QSPI	SSIE	ETHERC (MII) (25 MHz)	ETHERC (RMII) (50 MHz)	SDHI	ADC12	DAC12, ACMPHS	CTSU	PDC
E1	86	-	CLKOUT/CACREF	-	P611	-	SDCS	-	-	-	-	-	-	CTS7_RTS7/SS7	-	-	-	-	-	-	-	-	-	-
F2	87	-	-	-	P612	D08[A08/D08]	DQ08	-	-	-	-	-	-	SCK7	-	-	-	-	-	-	-	-	-	-
F1	88	-	-	-	P613	D09[A09/D09]	DQ09	-	-	-	-	-	-	TXD7	-	-	-	-	-	-	-	-	-	-
G3	89	-	-	-	P614	D10[A10/D10]	DQ10	-	-	-	-	-	-	RXD7	-	-	-	-	-	-	-	-	-	-
G1	90	62	VCC	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
G2	91	63	VSS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
H1	92	64	VCL	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
H2	93	-	-	-	P605	D11[A11/D11]	DQ11	-	-	GTIOC8A	-	-	-	-	-	-	-	-	-	-	-	-	-	-
G4	94	-	-	-	P604	D12[A12/D12]	DQ12	-	-	GTIOC8B	-	-	-	-	-	-	-	-	-	-	-	-	-	-
H3	95	-	-	-	P603	D13[A13/D13]	DQ13	-	-	GTIOC7A	-	-	-	CTS9_RTS9/SS9	-	-	-	-	-	-	-	-	-	-
J1	96	65	-	-	P602	EBCLK	SDCLK	-	-	GTIOC7B	-	-	-	TXD9	-	-	-	-	-	-	-	-	-	-
J2	97	66	-	-	P601	WR/WR0	DQM0	-	-	GTIOC6A	-	-	-	RXD9	-	-	-	-	-	-	-	-	-	-
H4	98	67	CLKOUT/CACREF	-	P600	RD	-	-	-	GTIOC6B	-	-	-	SCK9	-	-	-	-	-	-	-	-	-	-
K2	99	-	VCC	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
K1	100	-	VSS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
J3	101	68	-	KR07	P107	D07[A07/D07]	DQ07	AGTOA0	-	GTIOC8A	-	-	CTS8_RTS8/SS8	-	-	-	-	-	-	-	-	-	-	-
K3	102	69	-	KR06	P106	D06[A06/D06]	DQ06	AGTOB0	-	GTIOC8B	-	-	SCK8	-	-	SSLA3_A	-	-	-	-	-	-	-	-
J4	103	70	-	IRQ0/KR05	P105	D05[A05/D05]	DQ05	-	GTETRGA	GTIOC1A	-	-	TXD8/MOSI8/SDA8	-	-	SSLA2_A	-	-	-	-	-	-	-	-
L3	104	71	-	IRQ1/KR04	P104	D04[A04/D04]	DQ04	-	GTETRGB	GTIOC1B	-	-	RXD8/MISO8/SCL8	-	-	SSLA1_A	-	-	-	-	-	-	-	-
L1	105	72	-	KR03	P103	D03[A03/D03]	DQ03	-	GTOWUP	GTIOC2A_A	-	CTX0	CTS0_RTS0/SS0	-	-	SSLA0_A	-	-	-	-	-	-	-	-
M1	106	73	-	KR02	P102	D02[A02/D02]	DQ02	AGTO0	GTOWLO	GTIOC2B_A	-	CRX0	SCK0	-	-	RSPCKA_A	-	-	-	-	ADTRG0	-	-	-
M2	107	74	-	IRQ1/KR01	P101	D01[A01/D01]	DQ01	AGTEE0	GTETRGB	GTIOC5A	-	-	TXD0/MOSI0/SDA0	CTS1_RTS1/SS1	SDA1_B	MOSIA_A	-	-	-	-	-	-	-	-
N1	108	75	-	IRQ2/KR00	P100	D00[A00/D00]	DQ00	AGTIO0	GTETRGA	GTIOC5B	-	-	RXD0/MISO0/SCL0	SCK1	SCL1_B	MISOA_A	-	-	-	-	-	-	-	-
L2	109	-	-	-	P800	D14[A14/D14]	DQ14	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
N2	110	-	-	-	P801	D15[A15/D15]	DQ15	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
N3	111	-	VCC	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
M3	112	-	VSS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
K4	113	76	-	-	P500	-	-	AGTOA0	GTIU	GTIOC11A	-	USB_VBUSEN	-	-	-	QSPCLK	-	-	-	SD1CLK_A	AN016	IVREF0	-	-
M4	114	77	-	IRQ11	P501	-	-	AGTOB0	GTIV	GTIOC11B	-	USB_OVRCURA	-	TXD5/MOSI5/SDA5	-	QSSL	-	-	-	SD1CMD_A	AN116	IVREF1	-	-
L4	115	78	-	IRQ12	P502	-	-	-	GTIW	GTIOC12A	-	USB_OVRCURB	-	RXD5/MISO5/SCL5	-	QIO0	-	-	-	SD1DAT0_A	AN017	IVCMP0	-	-
K5	116	79	-	-	P503	-	-	-	GTETRGC	GTIOC12B	-	USB_EXICEN	CTS6_RTS6/SS6	SCK5	-	QIO1	-	-	-	SD1DAT1_A	AN117	-	-	-
L5	117	80	-	-	P504	ALE	-	-	GTETRGD	GTIOC13A	-	USB_ID	SCK6	CTS5_RTS5/SS5	-	QIO2	-	-	-	SD1DAT2_A	AN018	-	-	-
K6	118	-	-	IRQ14	P505	-	-	-	-	GTIOC13B	-	-	RXD6/MISO6/SCL6	-	-	QIO3	-	-	-	SD1DAT3_A	AN118	-	-	-
L6	119	-	-	IRQ15	P506	-	-	-	-	-	-	-	TXD6/MOSI6/SDA6	-	-	-	-	-	-	SD1CD	AN019	-	-	-
N4	120	81	-	-	P508	-	-	-	-	-	-	-	SCK6	SCK5	-	-	-	-	-	SD1DAT3_A	AN020	-	-	-
N5	121	82	VCC	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
M5	122	83	VSS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
M6	123	84	-	IRQ13	P015	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	AN006/AN106	DA1/IVCMP1	-	-
N6	124	85	-	-	P014	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	AN005/AN105	DA0/IVREF3	-	-
M7	125	86	VREFL	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-

Table 2.2 Recommended operating conditions

Item	Symbol	Value	Min	Typ	Max	Unit
Power supply voltages	VCC	When USB/SDRAM is not used	2.7	-	3.6	V
		When USB/SDRAM is used	3.0	-	3.6	V
	VSS		-	0	-	V
USB power supply voltages	VCC_USB		-	VCC	-	V
	VSS_USB		-	0	-	V
VBATT power supply voltage	VBATT		1.8	-	3.6	V
Analog power supply voltages	AVCC0*1		-	VCC	-	V
	AVSS0		-	0	-	V

Note 1. Connect AVCC0 to VCC. When the A/D converter, the D/A converter, or the comparator are not in use, do not leave the AVCC0, VREFH/VREFH0, AVSS0, and VREFL/VREFL0 pins open. Connect the AVCC0 and VREFH/VREFH0 pins to VCC, and the AVSS0 and VREFL/VREFL0 pins to VSS, respectively.

2.2 DC Characteristics

2.2.1 T_j/T_a Definition

Table 2.3 DC characteristics
Conditions: Products with operating temperature (T_a) –40 to +105°C.

Item	Symbol	Typ	Max	Unit	Test conditions
Permissible junction temperature	T_j	-	125	°C	High-speed mode Low-speed mode Subosc-speed mode
			105*1		

Note: Make sure that $T_j = T_a + \theta ja \times$ total power consumption (W),
where total power consumption = $(VCC - V_{OH}) \times \Sigma I_{OH} + V_{OL} \times \Sigma I_{OL} + I_{CC}max \times VCC$.

Note 1. The upper limit of operating temperature is 85°C or 105°C, depending on the product. For details, see section 1.3, Part Numbering. If the part number shows the operation temperature to 85°C, then Tj max is 105°C, otherwise, it is 125°C.

2.2.2 I/O V_{IH}, V_{IL}

Table 2.4 I/O V_{IH}, V_{IL} (1 of 2)

Item			Symbol	Min	Typ	Max	Unit
Input voltage (except for Schmitt trigger input pins)	Peripheral function pin	EXTAL(external clock input), WAIT, SPI (except RSPCK)	V_{IH}	VCC × 0.8	-	-	V
			V_{IL}	-	-	VCC × 0.2	
		D00 to D15, DQ00 to DQ15	V_{IH}	VCC × 0.7	-	-	
			V_{IL}	-	-	VCC × 0.3	
		ETHERC	V_{IH}	2.3	-	-	
			V_{IL}	-	-	VCC × 0.2	
		IIC (SMBus)*1	V_{IH}	2.1	-	-	
			V_{IL}	-	-	0.8	
		IIC (SMBus)*2	V_{IH}	2.1	-	VCC + 3.6 (max 5.8)	
			V_{IL}	-	-	0.8	
Schmitt trigger input voltage	Peripheral function pin	IIC (except for SMBus)*1	V_{IH}	VCC × 0.7	-	-	V
			V_{IL}	-	-	VCC × 0.3	
			ΔV_T	VCC × 0.05	-	-	

Table 2.12 Operation frequency value in Subosc-speed mode

Item		Symbol	Min	Typ	Max	Unit
Operation frequency	System clock (ICLK)*2	f	29.4	-	36.1	kHz
	Peripheral module clock (PCLKA)*2		-	-	36.1	
	Peripheral module clock (PCLKB)*2		-	-	36.1	
	Peripheral module clock (PCLKC)*2,*3		-	-	36.1	
	Peripheral module clock (PCLKD)*2		-	-	36.1	
	Flash interface clock (FCLK)*1, *2		29.4	-	36.1	
	External bus clock (BCLK)*2		-	-	36.1	
	EBCLK pin output		-	-	36.1	

Note 1. Programming or erasing the flash memory is disabled in Subosc-speed mode.
Note 2. See section 9, Clock Generation Circuit in User's Manual for the relationship between the ICLK, PCLKA, PCLKB, PCLKC, PCLKD, FCLK, and BCLK frequencies.
Note 3. The ADC12 cannot be used.

2.3.2 Clock Timing

Table 2.13 Clock timing except for sub-clock oscillator (1 of 2)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
EBCLK pin output cycle time	t_{Bcyc}	16.6	-	-	ns	Figure 2.7
EBCLK pin output high pulse width	t_{CH}	3.3	-	-	ns	
EBCLK pin output low pulse width	t_{CL}	3.3	-	-	ns	
EBCLK pin output rise time	t_{Cr}	-	-	5.0	ns	
EBCLK pin output fall time	t_{Cf}	-	-	5.0	ns	
SDCLK pin output cycle time	t_{SDcyc}	8.33	-	-	ns	
SDCLK pin output high pulse width	t_{CH}	1.0	-	-	ns	
SDCLK pin output low pulse width	t_{CL}	1.0	-	-	ns	
SDCLK pin output rise time	t_{Cr}	-	-	3.0	ns	
SDCLK pin output fall time	t_{Cf}	-	-	3.0	ns	
EXTAL external clock input cycle time	t_{EXcyc}	41.66	-	-	ns	Figure 2.8
EXTAL external clock input high pulse width	t_{EXH}	15.83	-	-	ns	
EXTAL external clock input low pulse width	t_{EXL}	15.83	-	-	ns	
EXTAL external clock rise time	t_{EXr}	-	-	5.0	ns	
EXTAL external clock fall time	t_{EXf}	-	-	5.0	ns	
Main clock oscillator frequency	f_{MAIN}	8	-	24	MHz	-
Main clock oscillation stabilization wait time (crystal) *1	$t_{MAINOSCWT}$	-	-	-*1	ms	Figure 2.9
LOCO clock oscillation frequency	f_{LOCO}	29.4912	32.768	36.0448	kHz	-
LOCO clock oscillation stabilization wait time	t_{LOCOWT}	-	-	60.4	µs	Figure 2.10
ILOCO clock oscillation frequency	f_{ILOCO}	13.5	15	16.5	kHz	-
MOCO clock oscillation frequency	F_{MOCO}	6.8	8	9.2	MHz	-
MOCO clock oscillation stabilization wait time	t_{MOCOWT}	-	-	15.0	µs	-

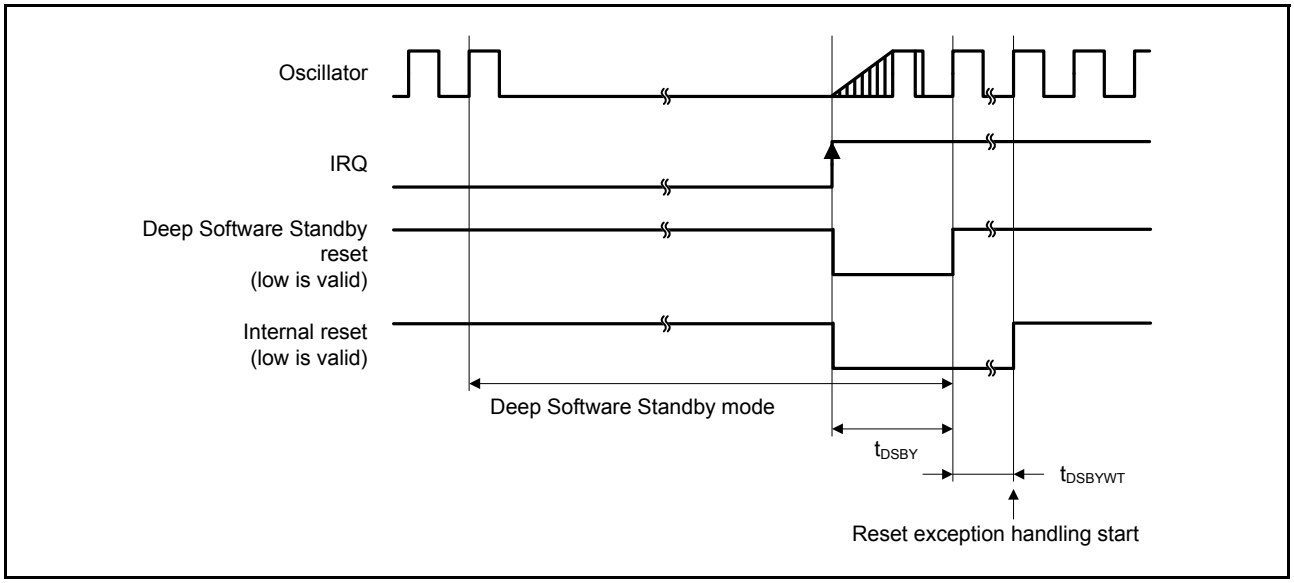


Figure 2.16 Deep Software Standby mode cancellation timing

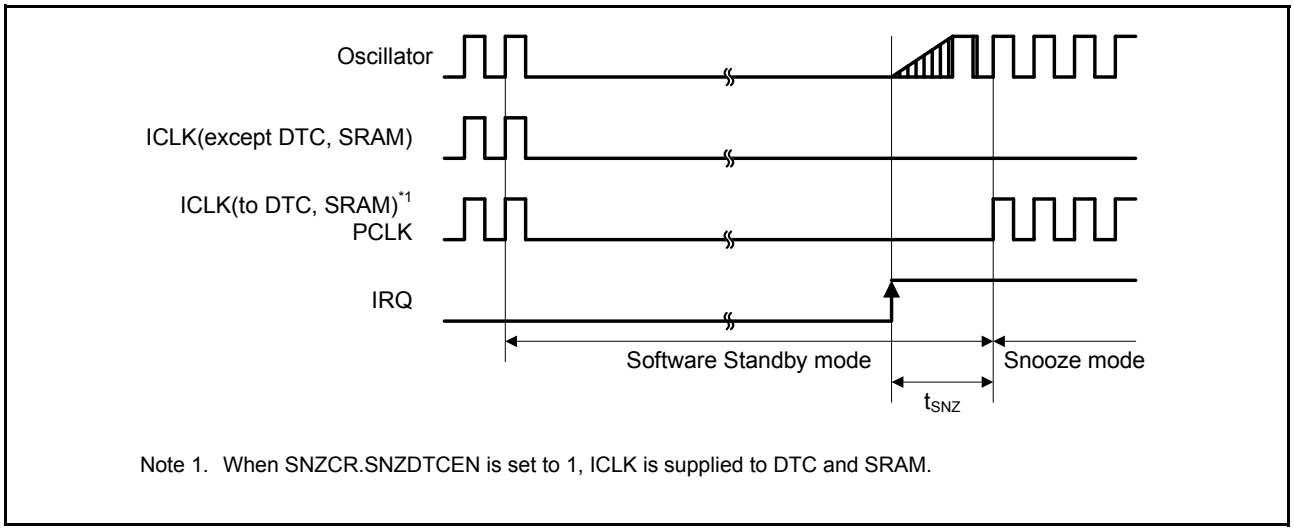


Figure 2.17 Recovery timing from Software Standby mode to Snooze mode

2.3.5 NMI and IRQ Noise Filter

Table 2.17 NMI and IRQ noise filter

Item	Symbol	Min	Typ	Max	Unit	Test conditions	
NMI pulse width	t_{NMIW}	200	-	-	ns	NMI digital filter disabled	$t_{Pcyc} \times 2 \leq 200$ ns
		$t_{Pcyc} \times 2$*1	-	-			$t_{Pcyc} \times 2 > 200$ ns
		200	-	-		NMI digital filter enabled	$t_{NMICK} \times 3 \leq 200$ ns
		$t_{NMICK} \times 3.5$*2	-	-			$t_{NMICK} \times 3 > 200$ ns
IRQ pulse width	t_{IRQW}	200	-	-	ns	IRQ digital filter disabled	$t_{Pcyc} \times 2 \leq 200$ ns
		$t_{Pcyc} \times 2$*1	-	-			$t_{Pcyc} \times 2 > 200$ ns
		200	-	-		IRQ digital filter enabled	$t_{IRQCK} \times 3 \leq 200$ ns
		$t_{IRQCK} \times 3.5$*3	-	-			$t_{IRQCK} \times 3 > 200$ ns

Note: 200 ns minimum in Software Standby mode.
Note 1. t_{Pcyc} indicates the PCLKB cycle.

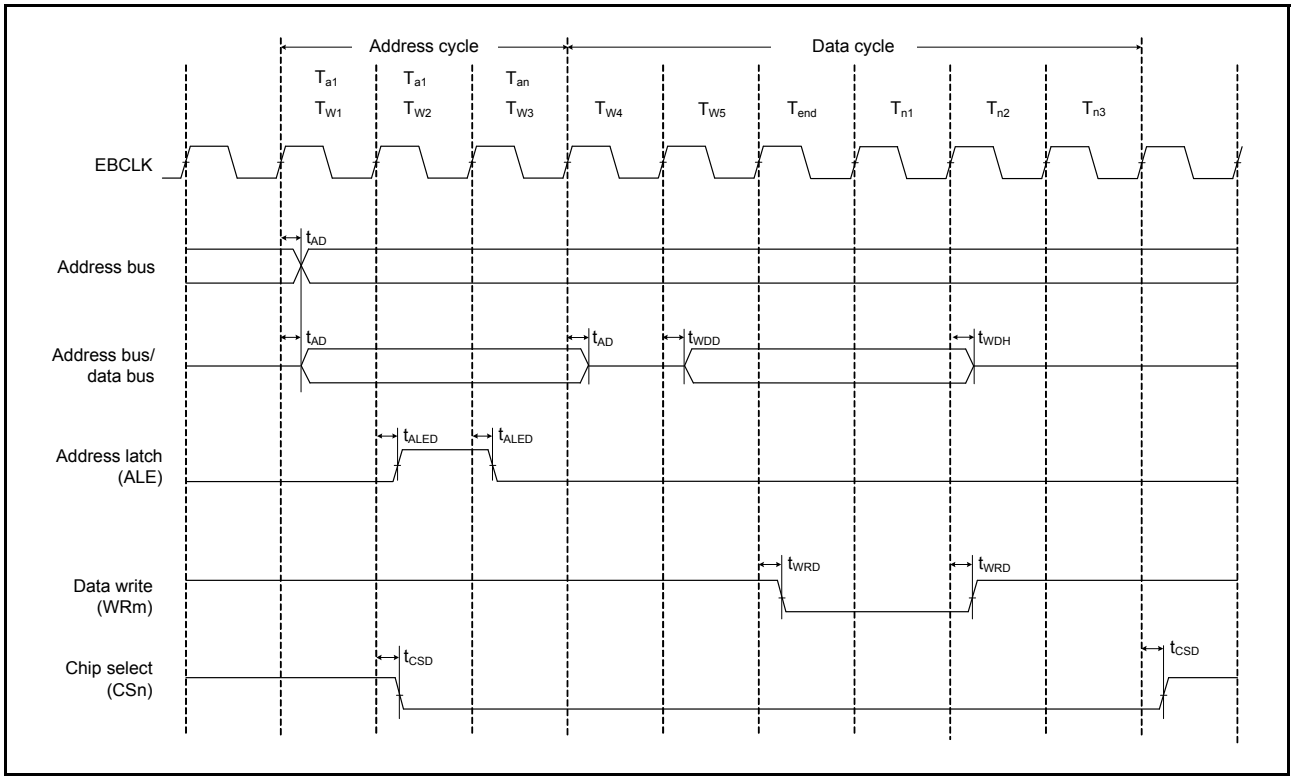


Figure 2.21 Address/data multiplexed bus write access timing

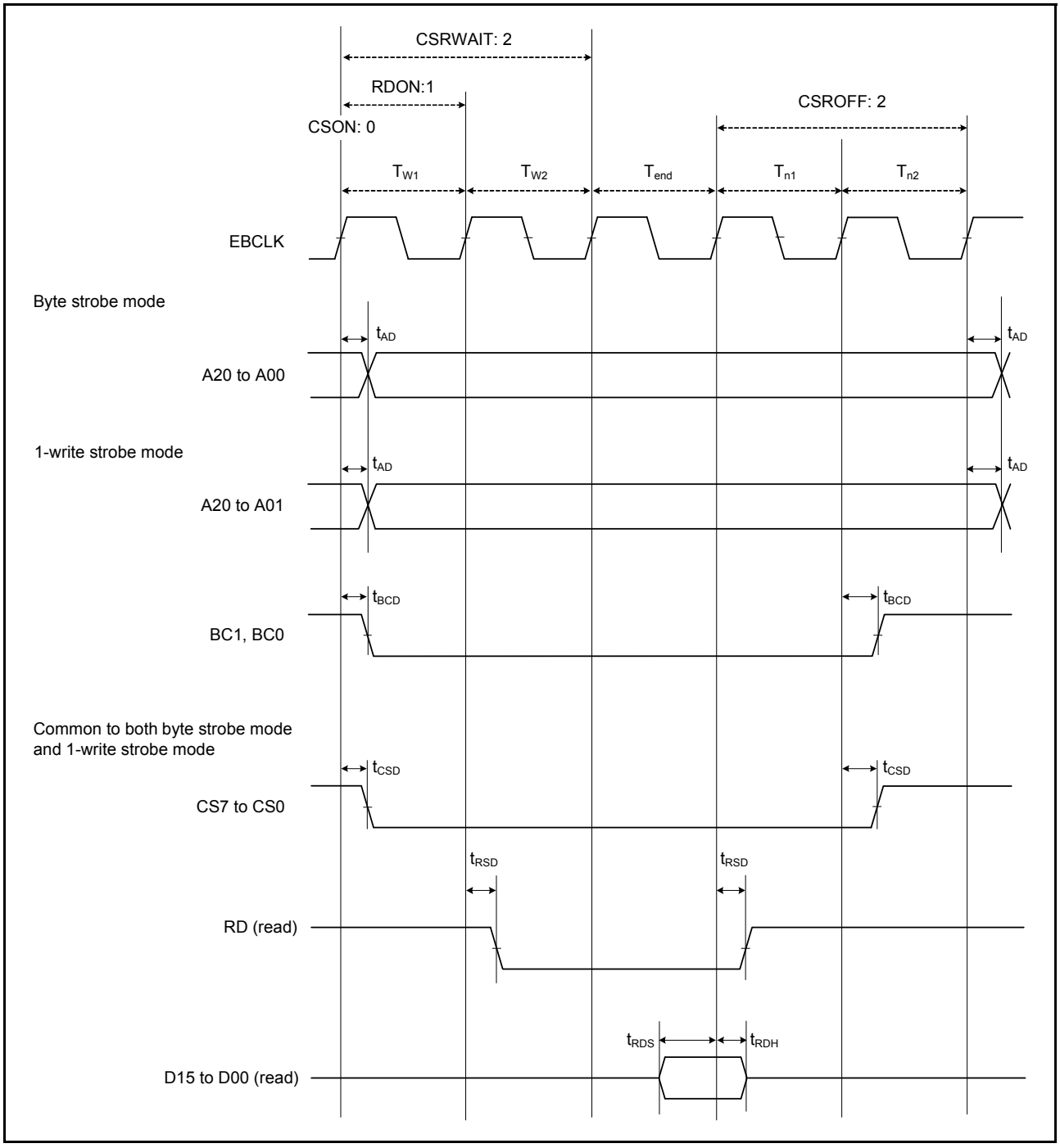
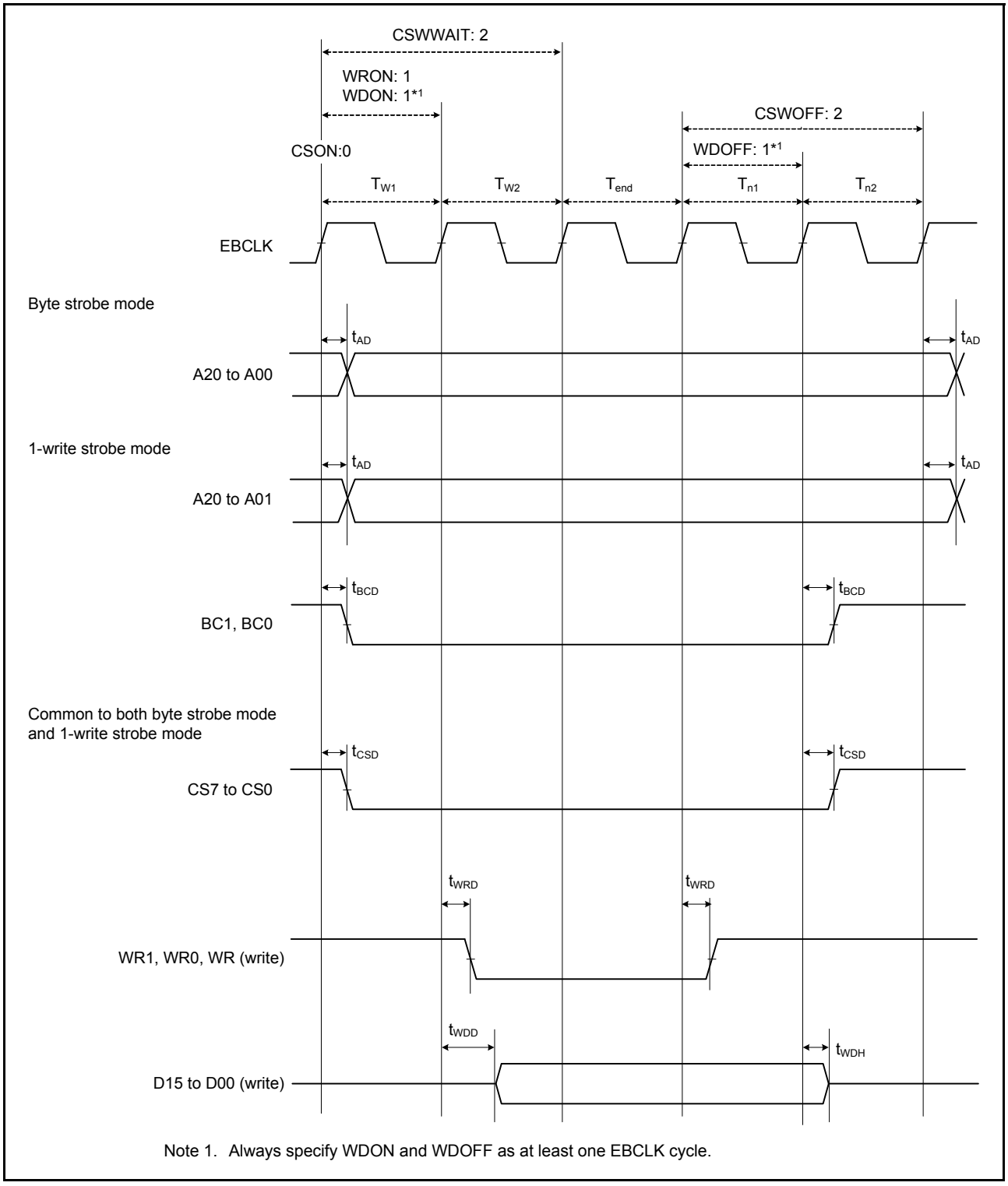
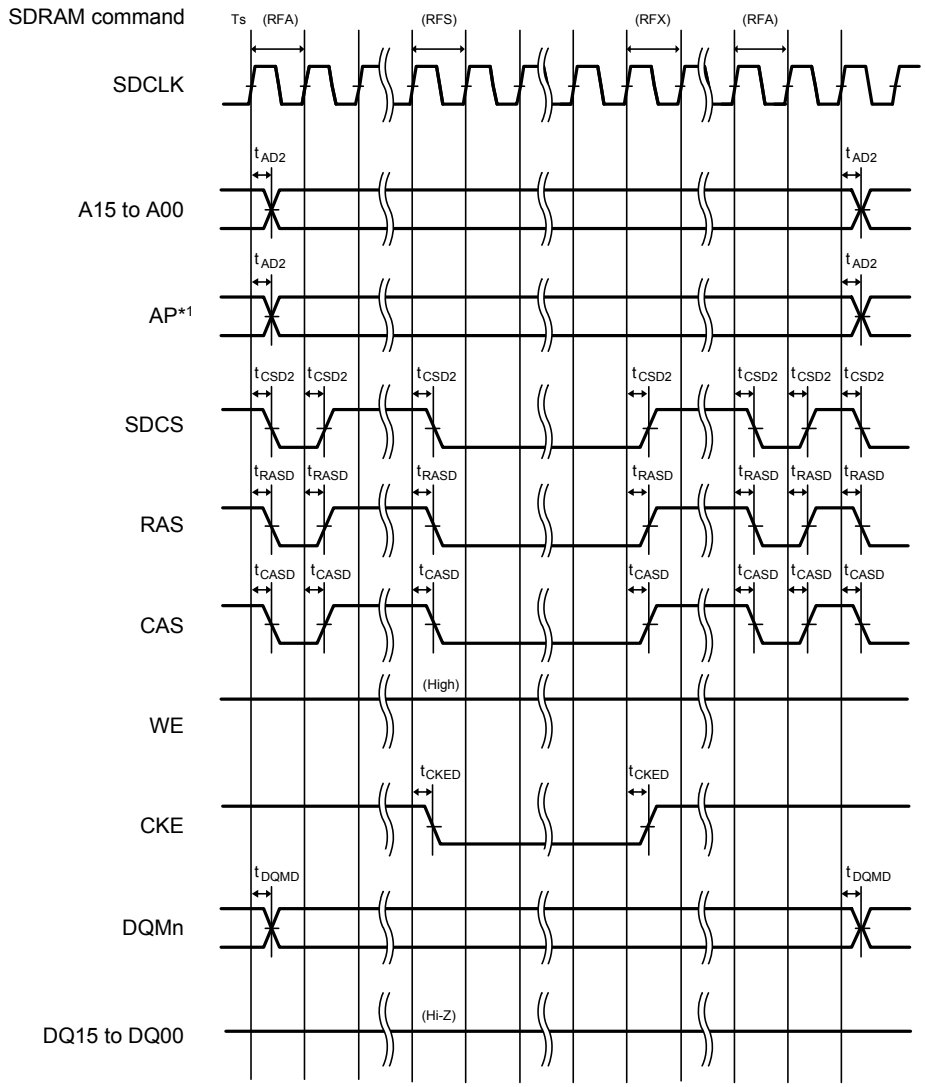


Figure 2.22 External bus timing for normal read cycle with bus clock synchronized



Note 1. Always specify WDON and WDOFF as at least one EBCLK cycle.

Figure 2.23 External bus timing for normal write cycle with bus clock synchronized



Note 1. Address pins are for output of the precharge-select command (Precharge-sel) for the SDRAM.

Figure 2.30 SDRAM self-refresh timing

2.3.7 I/O Ports, POEG, GPT32, AGT, KINT, and ADC12 Trigger Timing

Table 2.19 I/O ports, POEG, GPT32, AGT, KINT, and ADC12 trigger timing (1 of 2)

GPT32 Conditions:
High drive output is selected in the Port Drive Capability bit in the PmnPFS register.

AGT Conditions:
Middle drive output is selected in the Port Drive Capability bit in the PmnPFS register.

Item		Symbol	Min	Max	Unit	Test conditions
I/O ports	Input data pulse width	t_{PRW}	1.5	-	t_{Pcyc}	Figure 2.31
POEG	POEG input trigger pulse width	t_{POEW}	3	-	t_{Pcyc}	Figure 2.32

Note 1. t_{PBcyc}: PCLKB cycle.
Note 2. t_{cac}: CAC count clock source cycle.

2.3.10 SCI Timing

Table 2.22 SCI timing (1)
Conditions: High drive output is selected in the Port Drive Capability bit in the PmnPFS register for the following pins: SCK0 to SCK9. For other pins, middle drive output is selected in the Port Drive Capability bit in the PmnPFS register.

Item			Symbol	Min	Max	Unit*1	Test conditions
SCI	Input clock cycle	Asynchronous	t_{Scyc}	4	-	t_{Pcyc}	Figure 2.40
		Clock synchronous		6	-		
	Input clock pulse width		t_{SCKW}	0.4	0.6	t_{Scyc}	
	Input clock rise time		t_{SCKr}	-	5	ns	
	Input clock fall time		t_{SCKf}	-	5	ns	
	Output clock cycle	Asynchronous	t_{Scyc}	6	-	t_{Pcyc}	
		Clock synchronous		4	-		
	Output clock pulse width		t_{SCKW}	0.4	0.6	t_{Scyc}	
	Output clock rise time		t_{SCKr}	-	5	ns	
	Output clock fall time		t_{SCKf}	-	5	ns	
	Transmit data delay	Clock synchronous	t_{TXD}	-	25	ns	Figure 2.41
	Receive data setup time	Clock synchronous	t_{RXS}	15	-	ns	
	Receive data hold time	Clock synchronous	t_{RXH}	5	-	ns	

Note 1. t_{Pcyc}: PCLKA cycle.

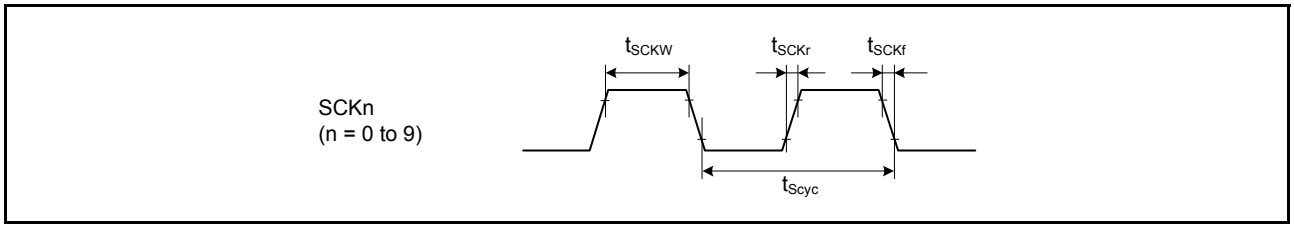


Figure 2.40 SCK clock input/output timing

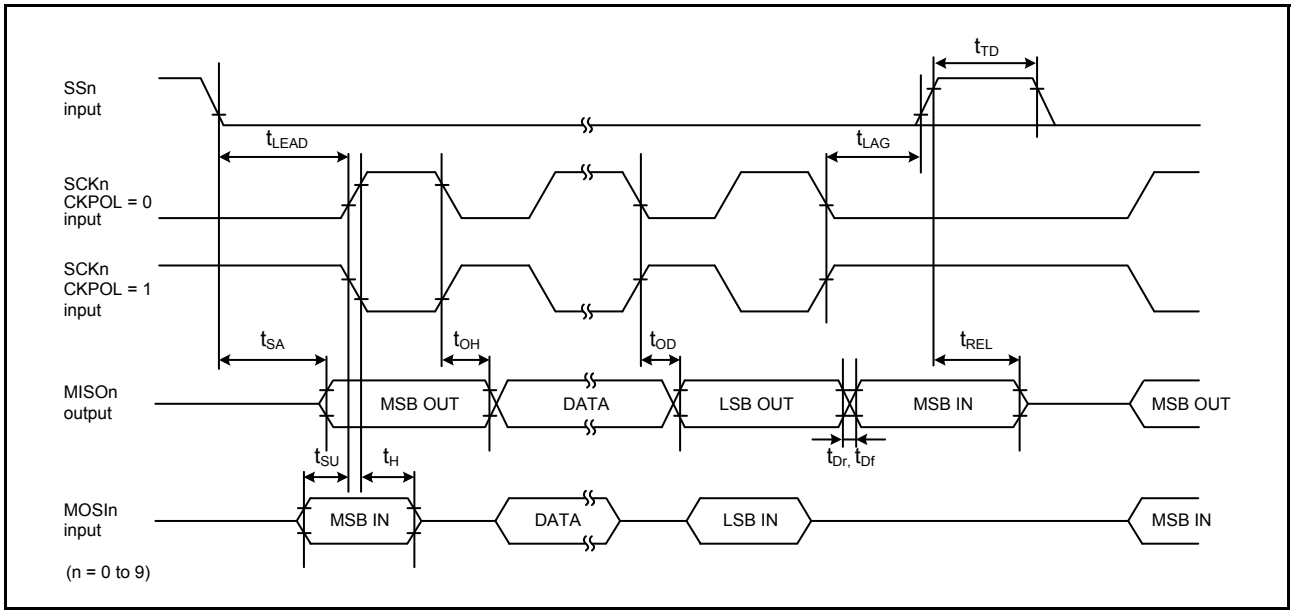


Figure 2.45 SCI simple SPI mode timing for slave when CKPH = 1

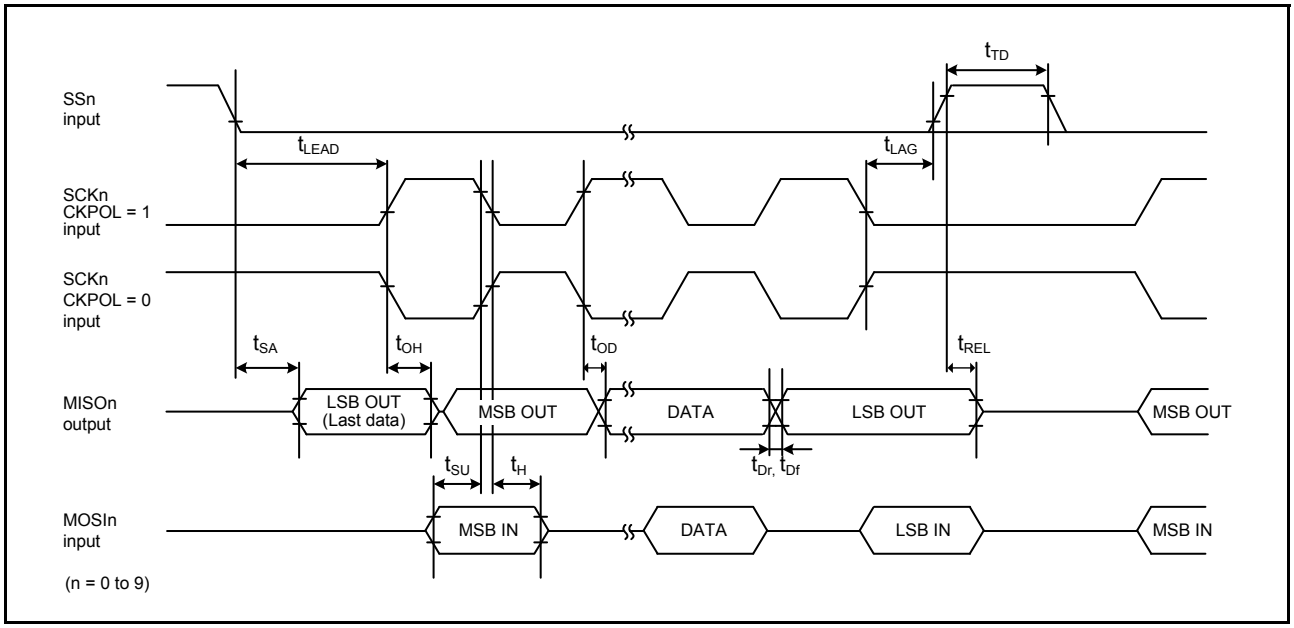


Figure 2.46 SCI simple SPI mode timing for slave when CKPH = 0

Table 2.24 SCI timing (3) (1 of 2)
Conditions: Middle drive output is selected in the Port Drive Capability bit in the PmnPFS register.

Item		Symbol	Min	Max	Unit	Test conditions
Simple IIC (Standard mode)	SDA input rise time	t_{Sr}	-	1000	ns	Figure 2.47
	SDA input fall time	t_{Sf}	-	300	ns	
	SDA input spike pulse removal time	t_{SP}	0	4 × t_{IICcyc}	ns	
	Data input setup time	t_{SDAS}	250	-	ns	
	Data input hold time	t_{SDAH}	0	-	ns	
	SCL, SDA capacitive load	C_{b}*1	-	400	pF	

2.3.11 SPI Timing

Table 2.25 SPI timing
Conditions:
For RSPCKA and RSPCKB pins, high drive output is selected with the Port Drive Capability bit in the PmnPFS register.
For other pins, middle drive output is selected in the Port Drive Capability bit in the PmnPFS register.

Item			Symbol	Min	Max	Unit*1	Test conditions*2
SPI	RSPCK clock cycle	Master	t_{SPcyc}	2 (PCLKA ≤ 60 MHz) 4 (PCLKA > 60 MHz)	4096	t_{Pcyc}	Figure 2.48 C = 30 pF
		Slave		4	4096		
	RSPCK clock high pulse width	Master	t_{SPCKWH}	$(t_{SPcyc} - t_{SPCKR} - t_{SPCKF}) / 2 - 3$	-	ns	
		Slave		$2 \times t_{Pcyc}$	-		
	RSPCK clock low pulse width	Master	t_{SPCKWL}	$(t_{SPcyc} - t_{SPCKR} - t_{SPCKF}) / 2 - 3$	-	ns	
		Slave		$2 \times t_{Pcyc}$	-		
	RSPCK clock rise and fall time	Master	t_{SPCKr}, t_{SPCKf}	-	5	ns	
		Slave		-	1	µs	
	Data input setup time	Master	t_{SU}	4	-	ns	Figure 2.49 to Figure 2.54 C = 30 pF
		Slave		5	-		
	Data input hold time	Master (PCLKA division ratio set to 1/2)	t_{HF}	0	-	ns	
		Master (PCLKA division ratio set to a value other than 1/2)	t_H	t_{Pcyc}	-		
		Slave	t_H	20	-		
	SSL setup time	Master	t_{LEAD}	$N \times t_{SPcyc}$ - 10*3	$N \times t_{SPcyc}$ + 100*3	ns	
		Slave		6 x t_{Pcyc}	-	ns	
	SSL hold time	Master	t_{LAG}	$N \times t_{SPcyc}$ - 10 *4	$N \times t_{SPcyc}$ + 100*4	ns	
		Slave		6 x t_{Pcyc}	-	ns	
	Data output delay	Master	t_{OD}	-	6.3	ns	
		Slave		-	20		
	Data output hold time	Master	t_{OH}	0	-	ns	
		Slave		0	-		
	Successive transmission delay	Master	t_{TD}	$t_{SPcyc} + 2 \times t_{Pcyc}$	$8 \times t_{SPcyc} + 2 \times t_{Pcyc}$	ns	
		Slave		$6 \times t_{Pcyc}$			
	MOSI and MISO rise and fall time	Output	t_{Dr}, t_{Df}	-	5	ns	
		Input		-	1	µs	
	SSL rise and fall time	Output	t_{SSLr}, t_{SSLf}	-	5	ns	
		Input		-	1	µs	
	Slave access time		t_{SA}	-	2 x t_{Pcyc} + 28	ns	Figure 2.53 and Figure 2.54 C = 30pF
	Slave output release time		t_{REL}	-	2 x t_{Pcyc} + 28		

Note 1. t_{Pcyc}: PCLKA cycle.

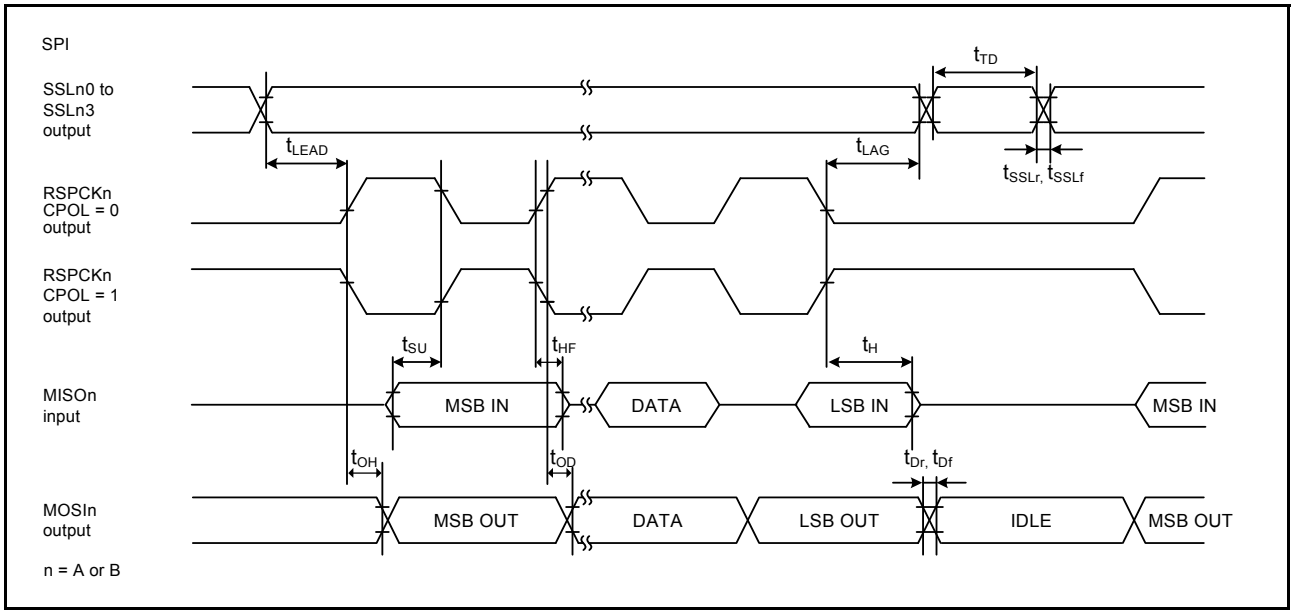


Figure 2.52 RSPI timing for master when CPHA = 1 and the bit rate is set to PCLKA/2

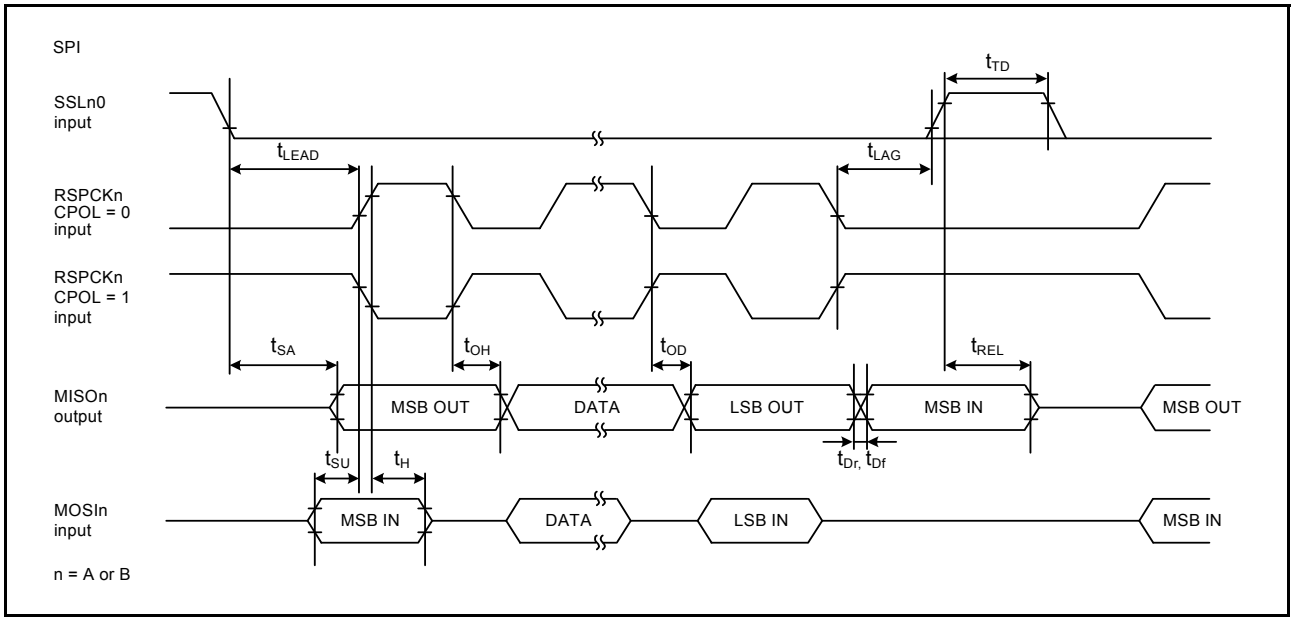


Figure 2.53 SPI timing for slave when CPHA = 0

For the SD/MMC Host interface, the AC portion of the electrical characteristics is measured for each group.

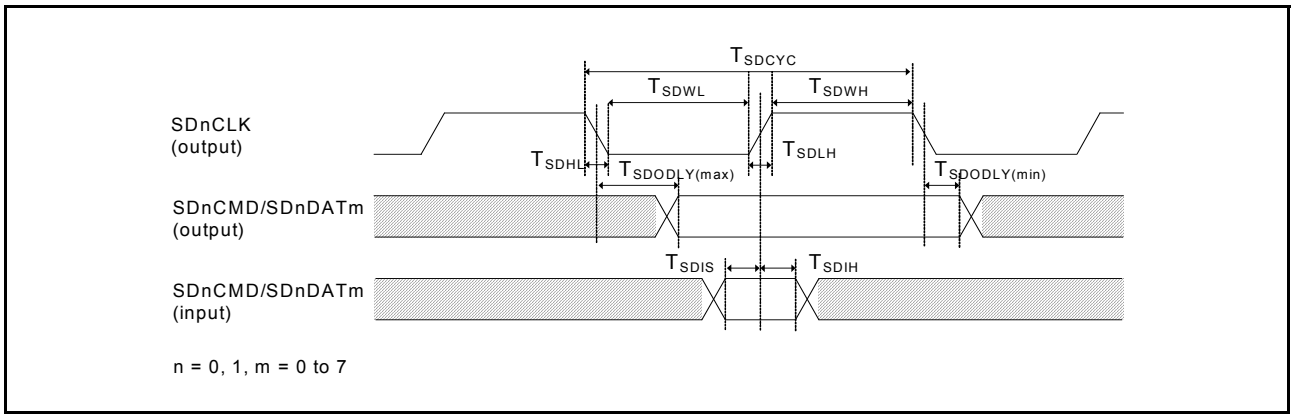


Figure 2.63 SD/MMC Host Interface signal timing

2.3.16 ETHERC Timing

Table 2.31 ETHERC timing

Conditions: ETHERC (RMII): Middle drive output is selected in the Port Drive Capability bit in the PmnPFS register for the following pins: ET0_MDC, ET0_MDIO.
For other pins, high drive output is selected in the Port Drive Capability bit in the PmnPFS register.
ETHERC (MII): Middle drive output is selected in the Port Drive Capability bit in the PmnPFS register.

Item		Symbol	Min	Max	Unit	Test conditions*3
ETHERC (RMII)	REF50CK0 cycle time	T_{ck}	20	-	ns	Figure 2.64 to Figure 2.67
	REF50CK0 frequency, typical 50 MHz	-	-	50 + 100 ppm	MHz	
	REF50CK0 duty	-	35	65	%	
	REF50CK0 rise/fall time	$T_{ckr/ckf}$	0.5	3.5	ns	
	RMII_xxxx*1 output delay	T_{co}	2.5	12.0	ns	
	RMII_xxxx*2 setup time	T_{su}	3	-	ns	
	RMII_xxxx*2 hold time	T_{hd}	1	-	ns	
	RMII_xxxx*1, *2 rise/fall time	T_r/T_f	0.5	4	ns	
	ET0_WOL output delay	t_{WOLd}	1	23.5	ns	Figure 2.68
ETHERC (MII)	ET0_TX_CLK cycle time	t_{Tcyc}	40	-	ns	-
	ET0_TX_EN output delay	t_{TENd}	1	20	ns	Figure 2.69
	ET0_ETXD0 to ET_ETXD3 output delay	t_{MTDd}	1	20	ns	
	ET0_CRS setup time	t_{CRSs}	10	-	ns	
	ET0_CRS hold time	t_{CRSh}	10	-	ns	
	ET0_COL setup time	t_{COLs}	10	-	ns	Figure 2.70
	ET0_COL hold time	t_{COLh}	10	-	ns	
	ET0_RX_CLK cycle time	t_{TRcyc}	40	-	ns	-
	ET0_RX_DV setup time	t_{RDVs}	10	-	ns	Figure 2.71
	ET0_RX_DV hold time	t_{RDVh}	10	-	ns	
	ET0_ERXD0 to ET_ERXD3 setup time	t_{MRDs}	10	-	ns	
	ET0_ERXD0 to ET_ERXD3 hold time	t_{MRDh}	10	-	ns	
	ET0_RX_ER setup time	t_{RERs}	10	-	ns	Figure 2.72
	ET0_RX_ER hold time	t_{RESh}	10	-	ns	
	ET0_WOL output delay	t_{WOLd}	1	23.5	ns	Figure 2.73

Note 1. RMII_TXD_EN, RMII_TXD1, RMII_TXD0.
Note 2. RMII_CRS_DV, RMII_RXD1, RMII_RXD0, RMII_RX_ER.

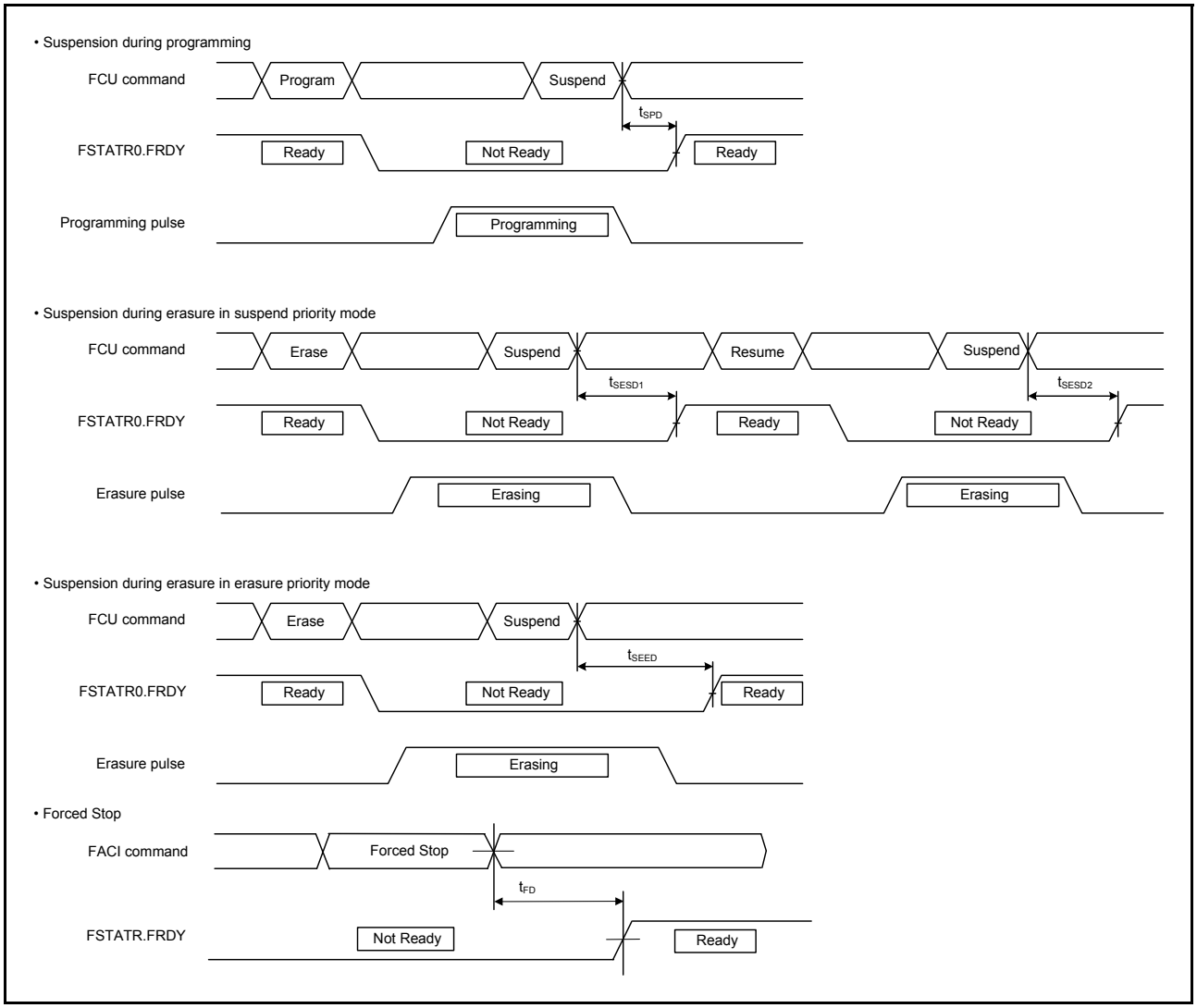


Figure 2.88 Suspension and forced stop timing for flash memory programming and erasure

Table 2.48 Boundary scan characteristics (2 of 2)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
TMS setup time	t_{TMSS}	20	-	-	ns	Figure 2.90
TMS hold time	t_{TMSH}	20	-	-	ns	
TDI setup time	t_{TDIS}	20	-	-	ns	
TDI hold time	t_{TDIH}	20	-	-	ns	
TDO data delay	t_{TDOD}	-	-	40	ns	
Boundary scan circuit startup time*1	T_{BSSTUP}	t_{RESWP}	-	-	-	Figure 2.91

Note 1. Boundary scan does not function until the power-on reset becomes negative.

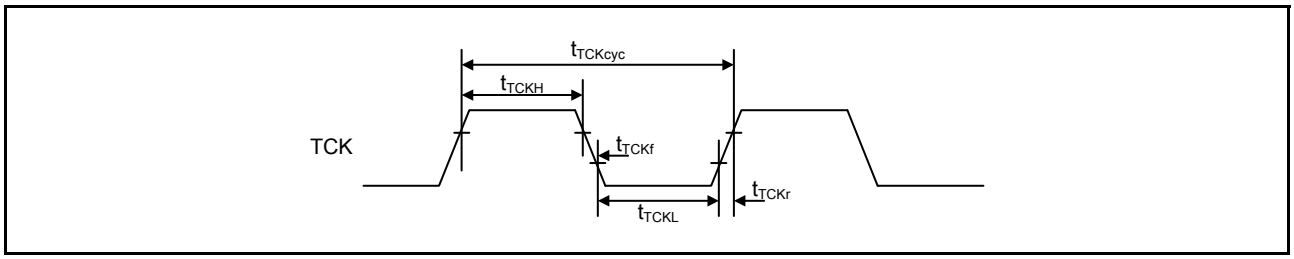


Figure 2.89 Boundary scan TCK timing

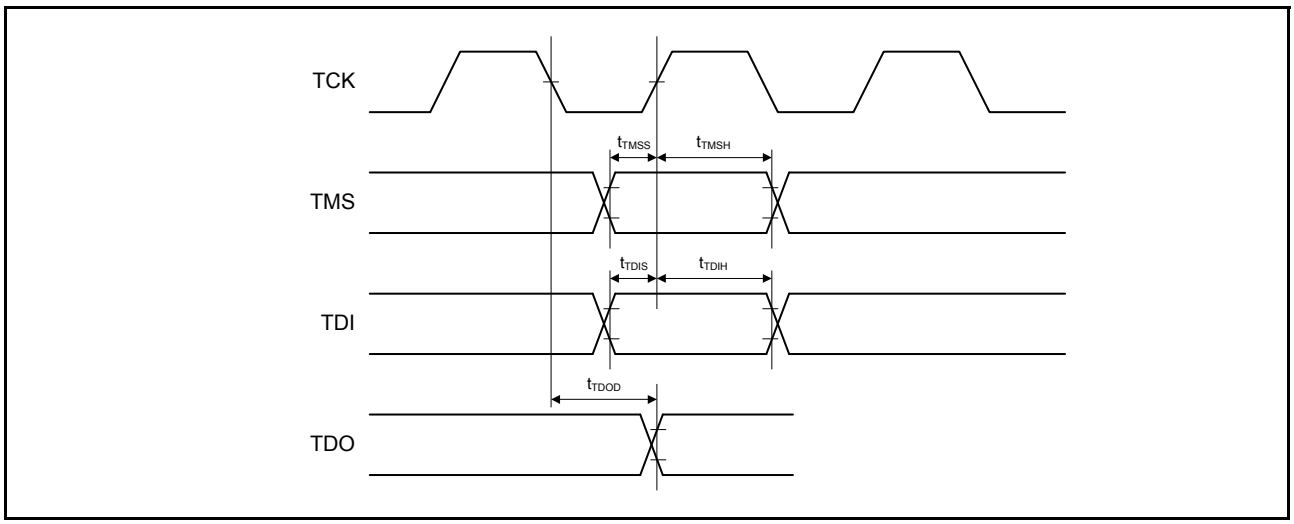


Figure 2.90 Boundary scan input/output timing

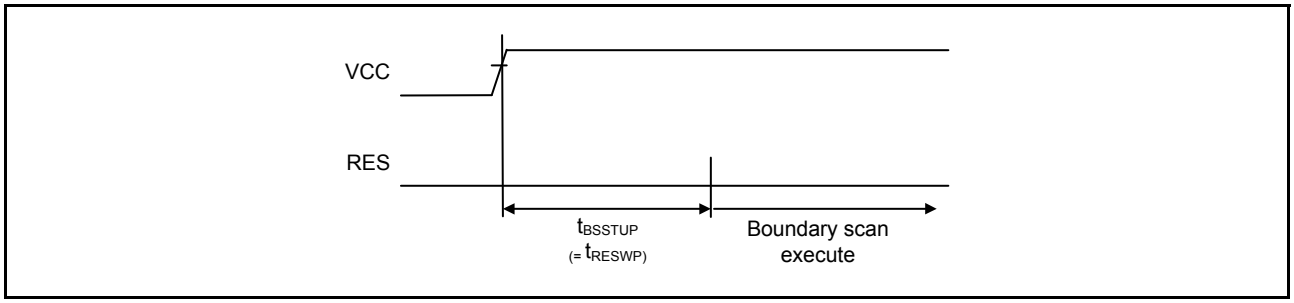
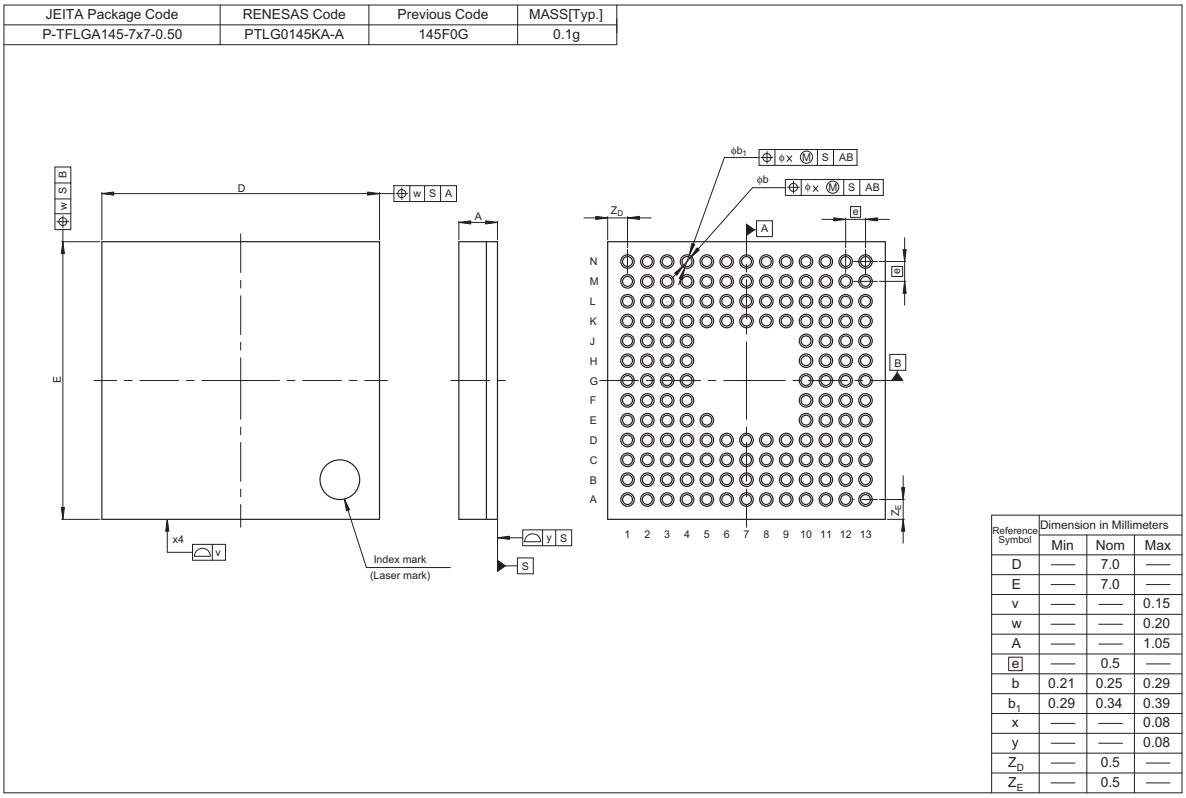


Figure 2.91 Boundary scan circuit startup timing

Appendix 1.Package Dimensions

For information on the latest version of the package dimensions or mountings, go to “Packages” on the Renesas Electronics Corporation website.

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-TFLGA145-7x7-0.50	PTLG0145KA-A	145F0G	0.1g



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	7.0	—
E	—	7.0	—
v	—	—	0.15
w	—	—	0.20
A	—	—	1.05
e	—	0.5	—
b	0.21	0.25	0.29
b_1	0.29	0.34	0.39
x	—	—	0.08
y	—	—	0.08
Z_D	—	0.5	—
Z_E	—	0.5	—

Figure 1.1 145-pin LGA

Renesas Synergy™ Platform
S5D5 Microcontroller Group

Renesas Electronics Corporation

R01DS0317EU0110